

1. Product Information

Supplier: JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number:	BSS123
Package Type:	SOT-23
Part Description:	SMD/MOSFET
Report Date:	June-2025

2. Reliability Test Results: PASS

Test Item	Test Condition	Duration	Fail Quantity / S.S
Pre-and post-stress Electrical test	Ta=25°C	—	All parts
PC Precondition(For SMD Package Only)	JESD22-A113F/J-STD-020 1.Bake:125°C 2.Soak: 85°C85%RH,168Hours MSL1 or 30°C60%RH,192Hours MSL3 3.Reflow 3Cycles Max 260°C 4.all samples E-Test	>168Hours or >192Hours	0 / 308
TCT Temperature Cycling Test	JESD22 -A104 -55°C/15min 150°C/15min	1000Cycles	0 / 77
AC Autoclave	JESD22-A102 121°C, 100%RH	96Hours	0 / 77
UHASt Unbaised Highly Accelerated Stress Test	JESD22-A118 130°C, 85%RH	96Hours	—
THt High Humidity &Temp. Test	JESD22-A101 85°C 85%RH	1000Hours	0 / 77
HTSt High Temperature Storage Test	JESD22 -A103 T=Tstg max	1000Hours	0 / 77
H3TRB High Humidity &Temp. Bias Test	JESD22-A101 85°C 85%RH VDS*80% VDS≤100V Max	1000Hours	—
HASt Highly Accelerated Stress Test	JESD22-A110 130°C 85%RH VDS*80% VDS≤42V Max	96Hours	0 / 77
HTRB High Temperature Revers Bias Test	JESD22 -A108 Tj(max), VDS*80%	1000Hours	0 / 77
HTGB High Temperature Gate Bias Test	JESD22 -A108 Tj(max), VGS*100%	1000Hours	0 / 77
IOL Intermittent Operational Life	MIL-STD-750D Method 1037 ΔTj≥100°C, On/Off:2min	15000Cycles	0 / 77
RSH Resistance to Solder Heat test	JESD22-A111B 260°C±5°C, 10(+2,-0)Seconds	—	0 / 30
SD Solderability	J-STD-002 1.Steam aging: 93°C 8Hours 2.245°C 3~5s	—	0 / 10

Notes:

1. Either H3TRB or HASt for reliability test.
2. Either AC or UHASt for reliability test.
3. Detailed MSL of the product refers to the MSL Report.

Remark: JSCJ Laboratory reserves the right of final interpretation of this report